

Application No.: 10/616,085
Amendment dated: September 21, 2005
Reply to Office Action of July 21, 2005

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

Claims 1-18 (Canceled)

19. (Currently Amended) A method of fabricating a device, comprising:

fabricating an integrated circuit chip, the integrated circuit chip including

a plurality of electrical bond pads;

fabricating a substrate;

positioning the integrated circuit chip relative to the substrate;

providing electrical connection between the integrated circuit chip and the

substrate during a reflow operation;

providing an underfill composition between the integrated circuit chip and the

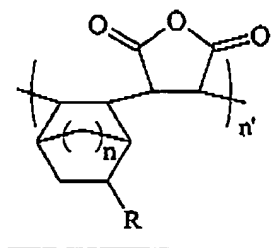
substrate, the underfill composition including

a resin; and

a curing agent selected from the group consisting of low molecular weight

maleic anhydride polymers comprising cyclohexane or bridged

cyclohexane having the following structural formula,

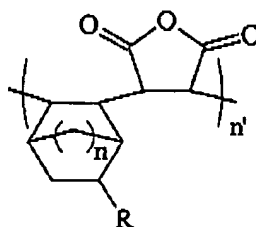


where n is 0, 2 or 3, n' is 5 to 50, and R is selected from the group

consisting of alkyl, aryl, substituted aryls, esters, ethers, lactones,

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anhydrides, alcohols, nitriles, epoxy, carboxylic acids and mixtures thereof, low molecular weight maleic anhydride oligomers, and a mixture thereof, wherein if the maleic anhydride polymers polymer is a copolymer comprising norbornene, then the copolymer has having the following structural formula:



where n is 1 to 3, n' is 5 to 50, and R is selected from the group consisting of ethers, lactones, anhydrides, alcohols, nitriles, epoxy, carboxylic acids, and maleic anhydride polymers comprising styrene having a molecular weight of about 1600 g/mole, and mixtures thereof, and wherein the molecular weight of the curing agent is greater than about 1000 g/mole.

20. (Original) The method according to claim 19 wherein the underfill composition is provided simultaneously during reflow.
21. (Original) The method according to claim 19 wherein the underfill composition is provided after reflow.
22. (Original) The method according to claim 19 wherein the underfill composition is cured.

Application No.: 10/616,085
Amendment dated: September 21, 2005
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22. (Original) The method according to claim 19 wherein the underfill composition is cured.
23. (Previously Presented) The method according to claim 22 wherein the curing occurs within a temperature range of from about 130° C to about 170° C.
24. (Previously Presented) The method according to claim 22 wherein the curing occurs within about 5 minutes to about 4 hours.
25. (Canceled)